

Title (en)

Activating a substrate for electroless plating.

Title (de)

Aktivierung eines Basismaterials vor der chemischen Metallisierung.

Title (fr)

Activation d'un substrat en vue d'une métallisation par voie chimique.

Publication

**EP 0158890 A2 19851023 (EN)**

Application

**EP 85103734 A 19850329**

Priority

US 59912084 A 19840411

Abstract (en)

A dielectric surface is conditioned for electroless plating of a conductive metal thereon by contacting the surface with a colloid of a precious metal and tin and then contacting the surface with a salt of ethylene diamine tetraacetic acid and/or of diethylene triamine pentaacetic acid.

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**C23C 18/28**

IPC 8 full level

**C23C 18/28** (2006.01); **H05K 3/18** (2006.01)

CPC (source: EP)

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Cited by

CN105671526A; AT395022B; GB2206128A; US4981720A; US5050978A; GB2206128B; WO9221790A1

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